

PCB Specification

PCB Layer	04 Layers
PCB Thickness	1.6 T
Copper Thickness	X.X 0Z
Material Type	FR-4
PCB Size	57 x 35 mm

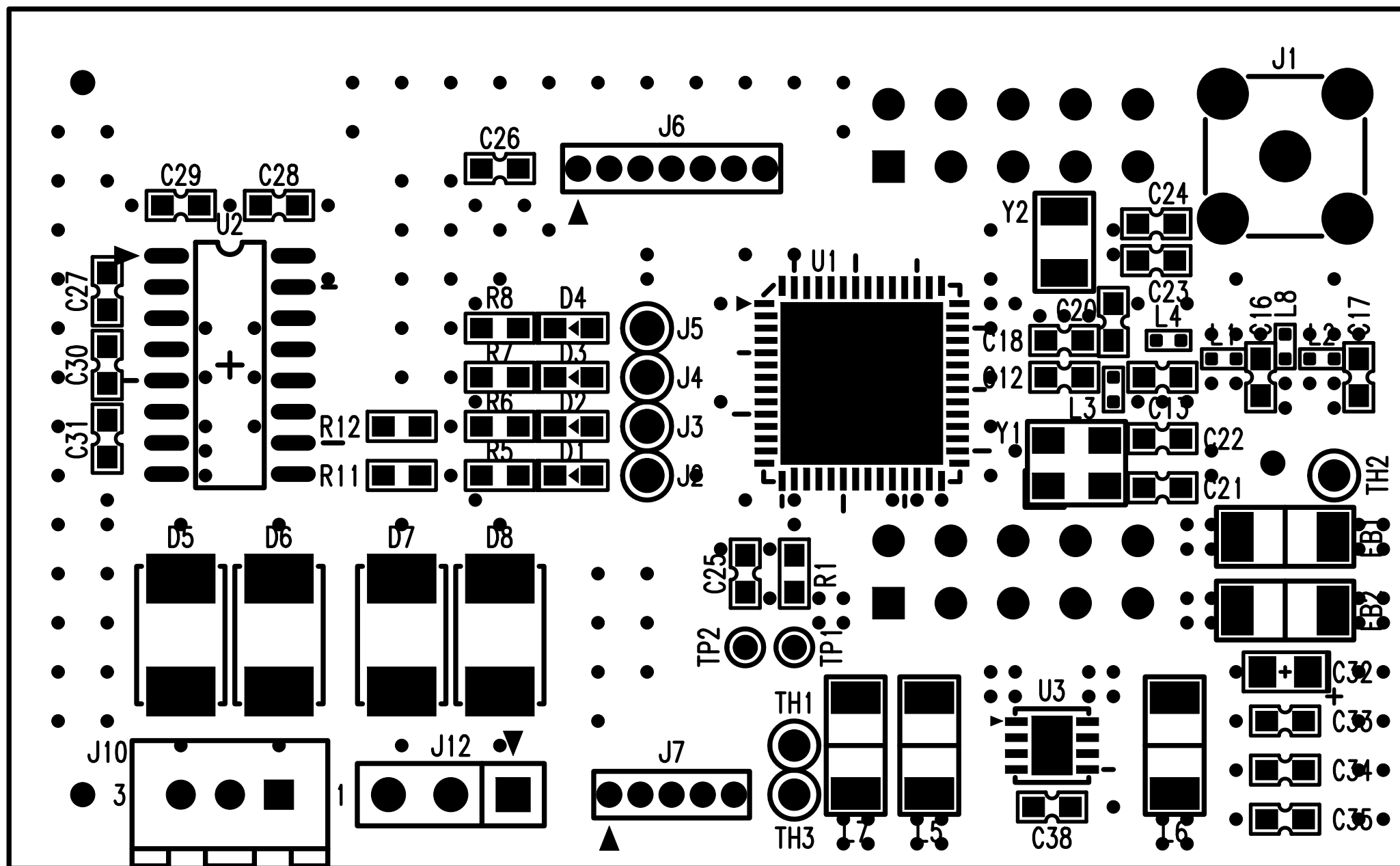
BOARD's DRILL SCHEDULE

TOOL	DRILL SYMBOL	DRILL SIZE	COUNT	PLATED
T1	A	0.300	218	YES
T2	B	0.650	12	YES
T3	C	0.800	3	YES
T4	D	0.900	23	YES
T5	E	1.000	7	YES
T6	F	1.500	5	YES

SMART KOREA IMPEDANCE 1.6T 04Layers SPEC.

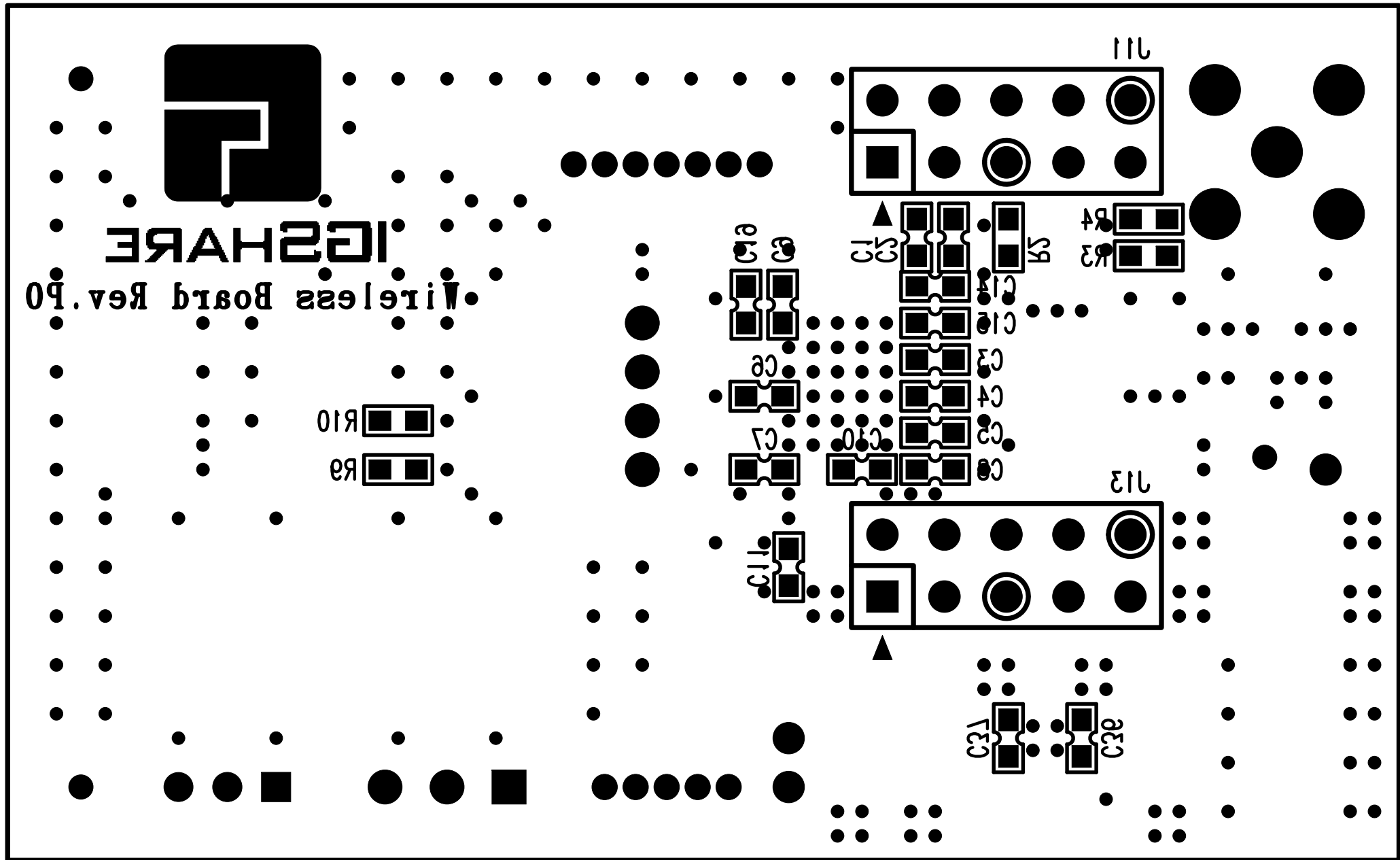
	SILK 1	RF 50ohm			Stackup Construction
	MASK 1		Width	GND GAP	
LAYER_1	COMP_SIDE	Impedance	0.53	0.285	<p>0.5 oz 0.11T P.P 0.18T P.P</p> <p>1.0T 1/1</p> <p>0.18T P.P 0.5 oz</p>
LAYER_2	GND	Reference			
LAYER_3	VCC				
LAYER_4	SOLD_SIDE				
	MASK 2	Unit : mm			
	SILK 2				

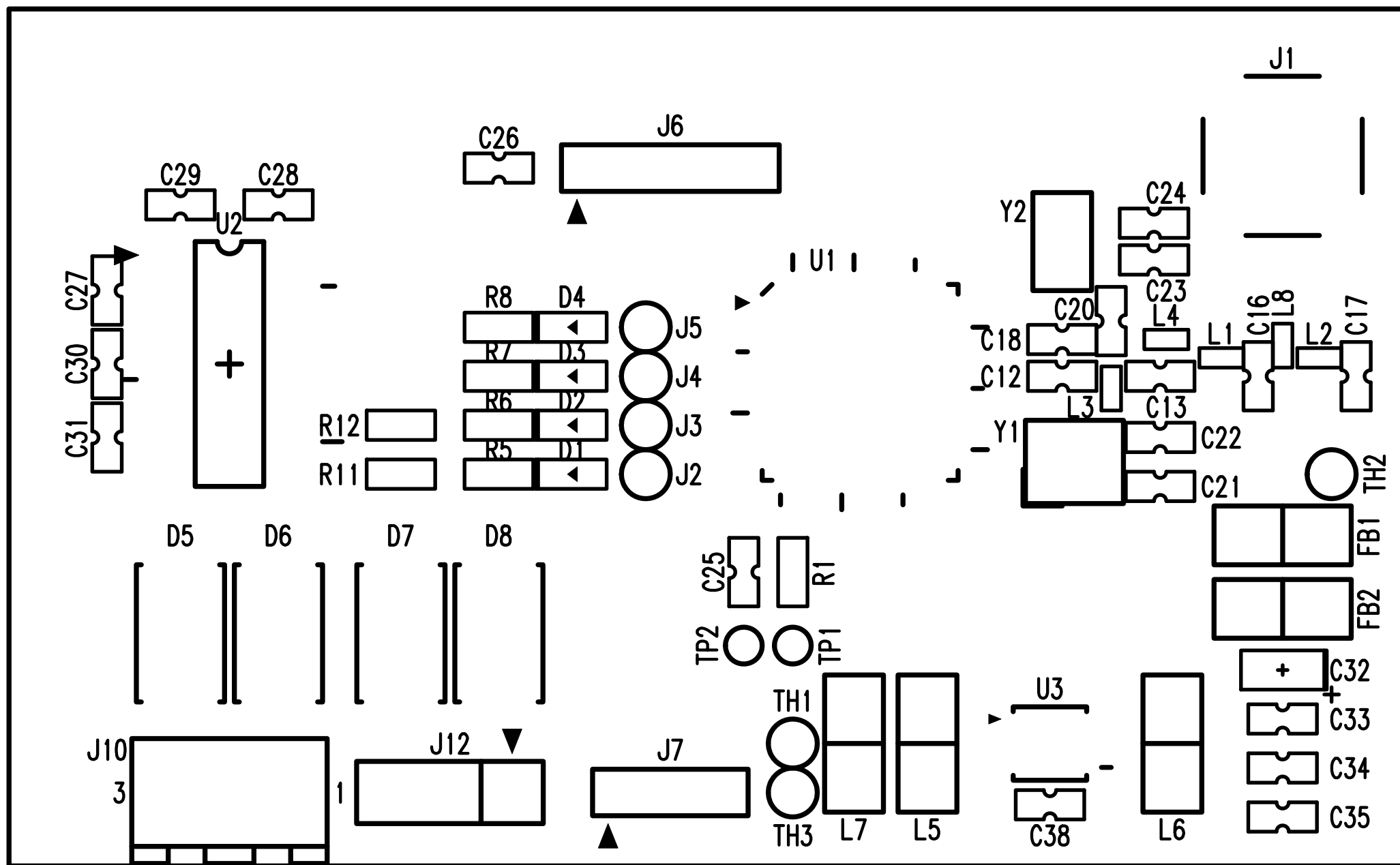
DRAWN	CUSTOMER IGShare	
CHECK-1	MODEL NAME WB	
CHECK-2		
DATE 2016.10.04	DRAWING NUMBER	FSCM NO.
UPDATE	UNIT - mm	REV.
InterNex CAD DIVISION		TEL: (02) 553-2273.4 FAX: (02) 569-2873





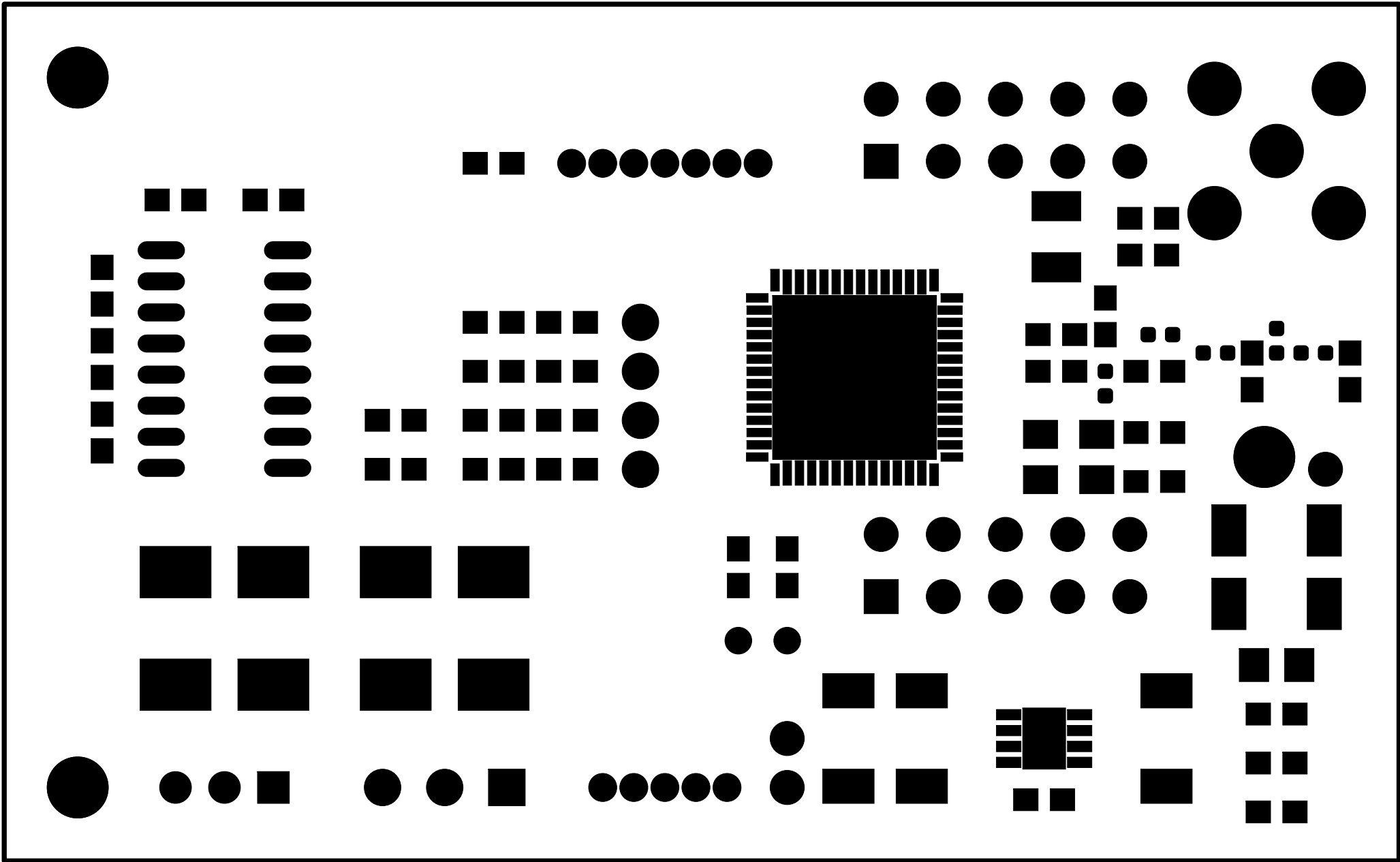
MODEL NAME	LAYER NAME	DATE
WB	ASSY2	2016.10.04







MODEL NAME	LAYER NAME	DATE
WB	MASK 1	2016.10.04





MODEL NAME

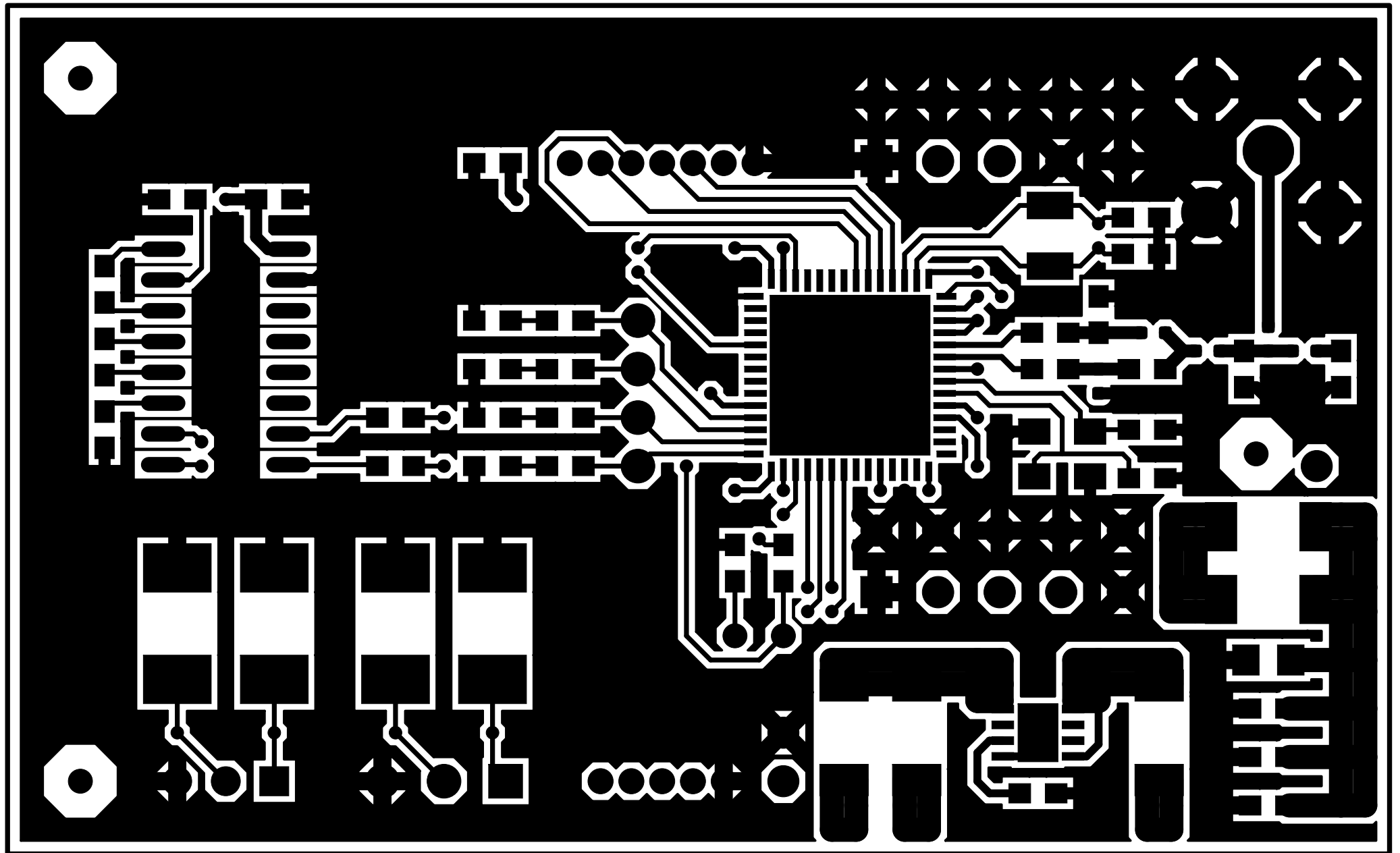
LAYER NAME

DATE

WB

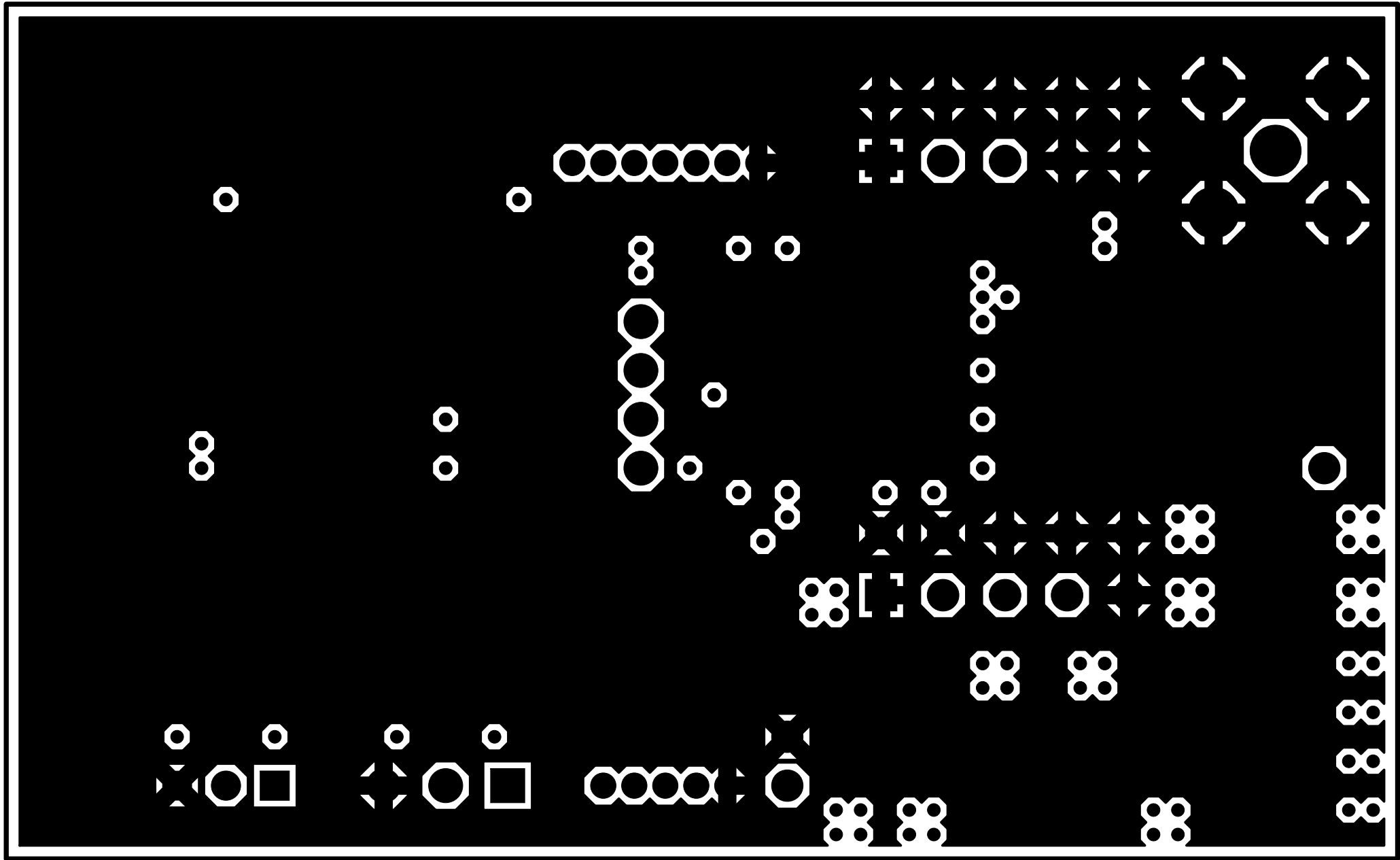
COMP

2016.10.04





MODEL NAME	LAYER NAME	DATE
WB	GND	2016.10.04





MODEL NAME

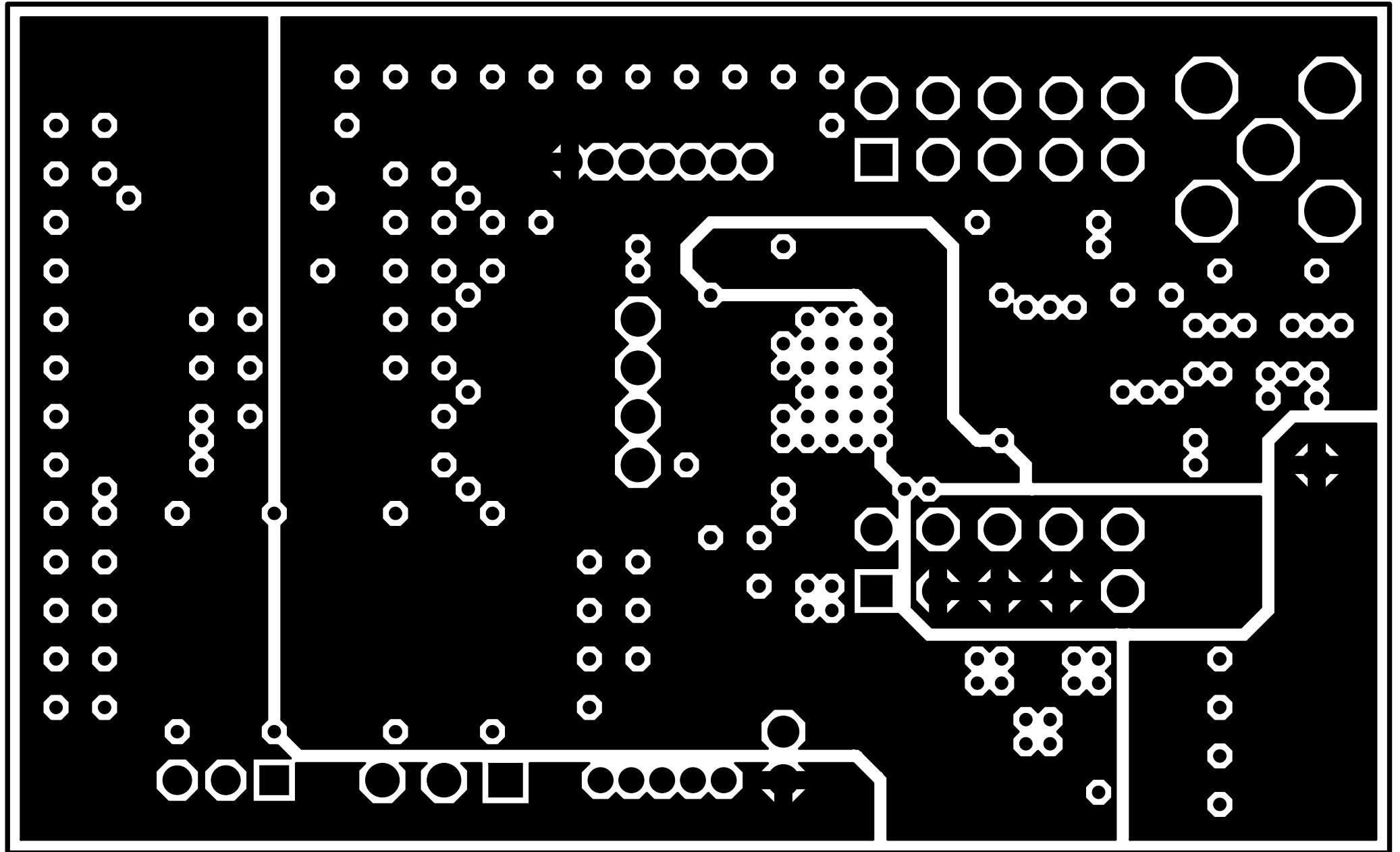
LAYER NAME

DATE

WB

VCC

2016.10.04





MODEL NAME

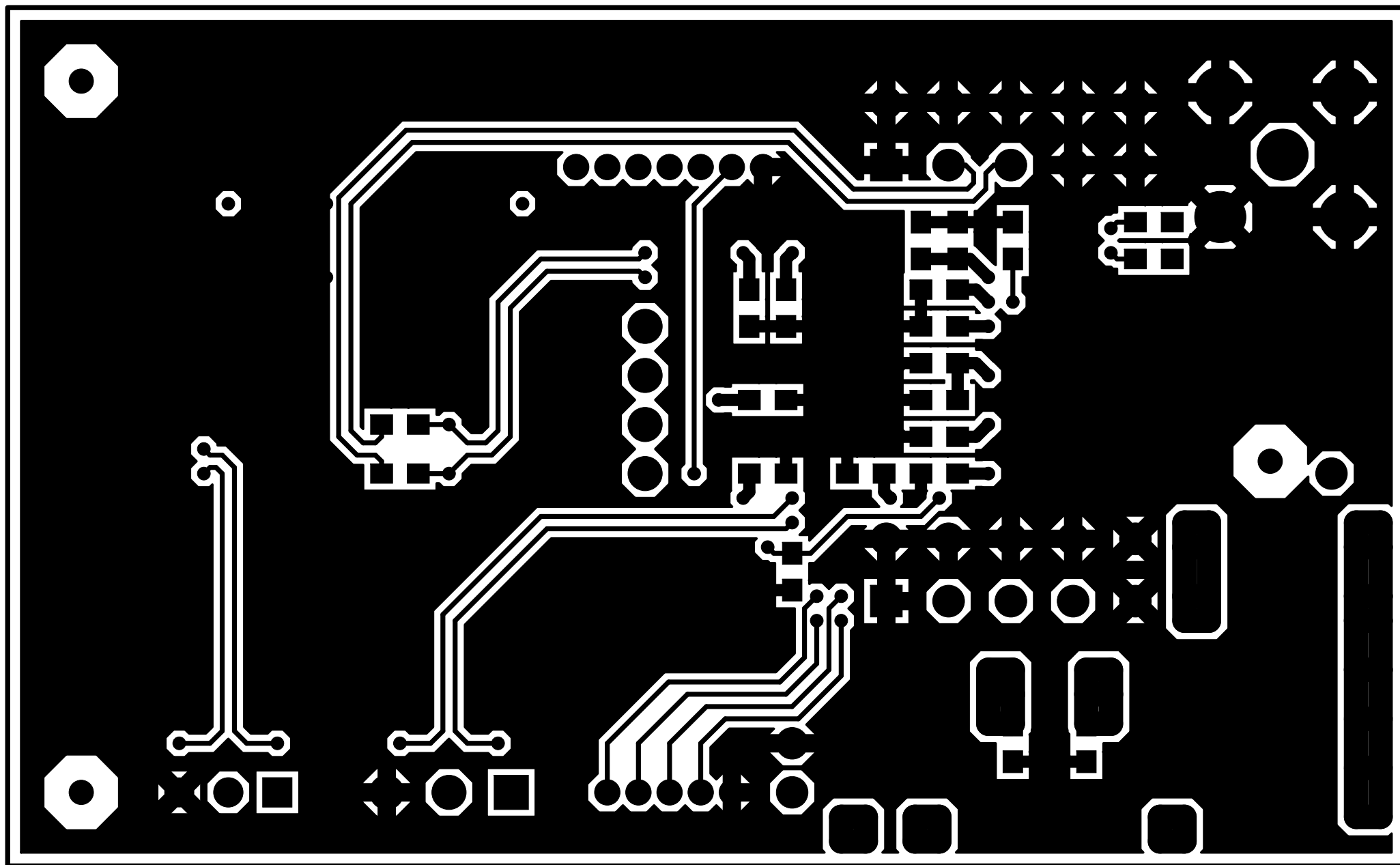
LAYER NAME

DATE

WB

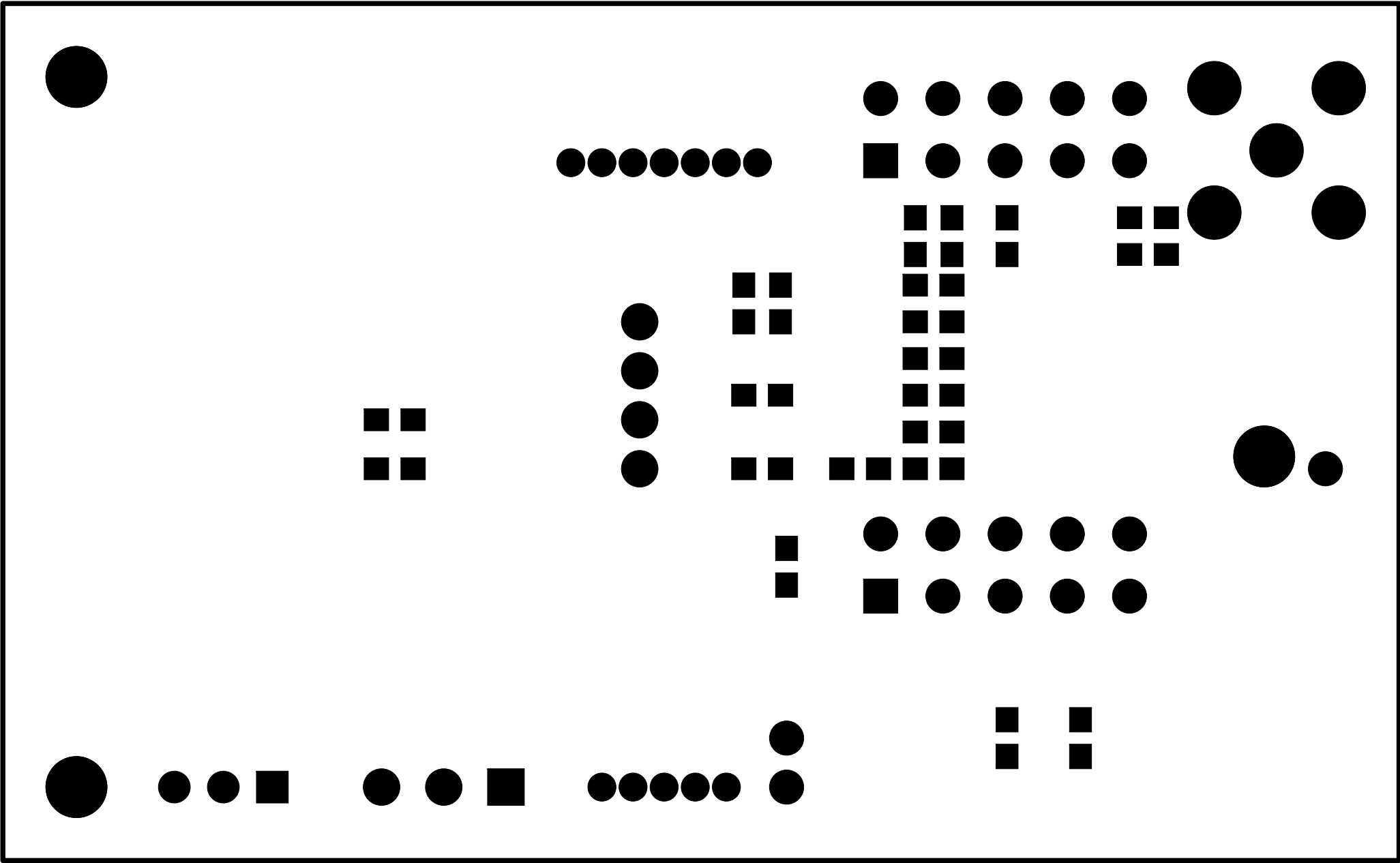
SOLD

2016.10.04



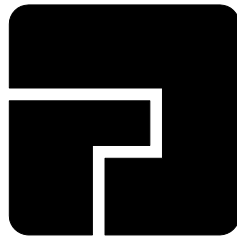


MODEL NAME	LAYER NAME	DATE
WB	MASK2	2016.10.04





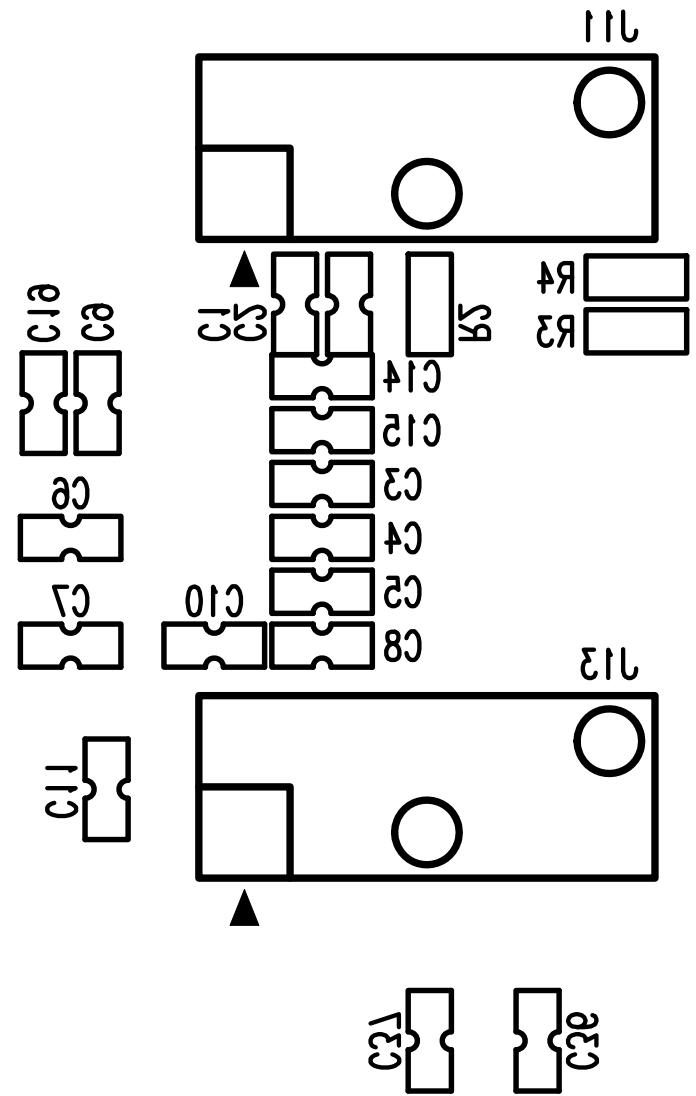
MODEL NAME	LAYER NAME	DATE
WB	SILK2	2016.10.04



IGSHARE

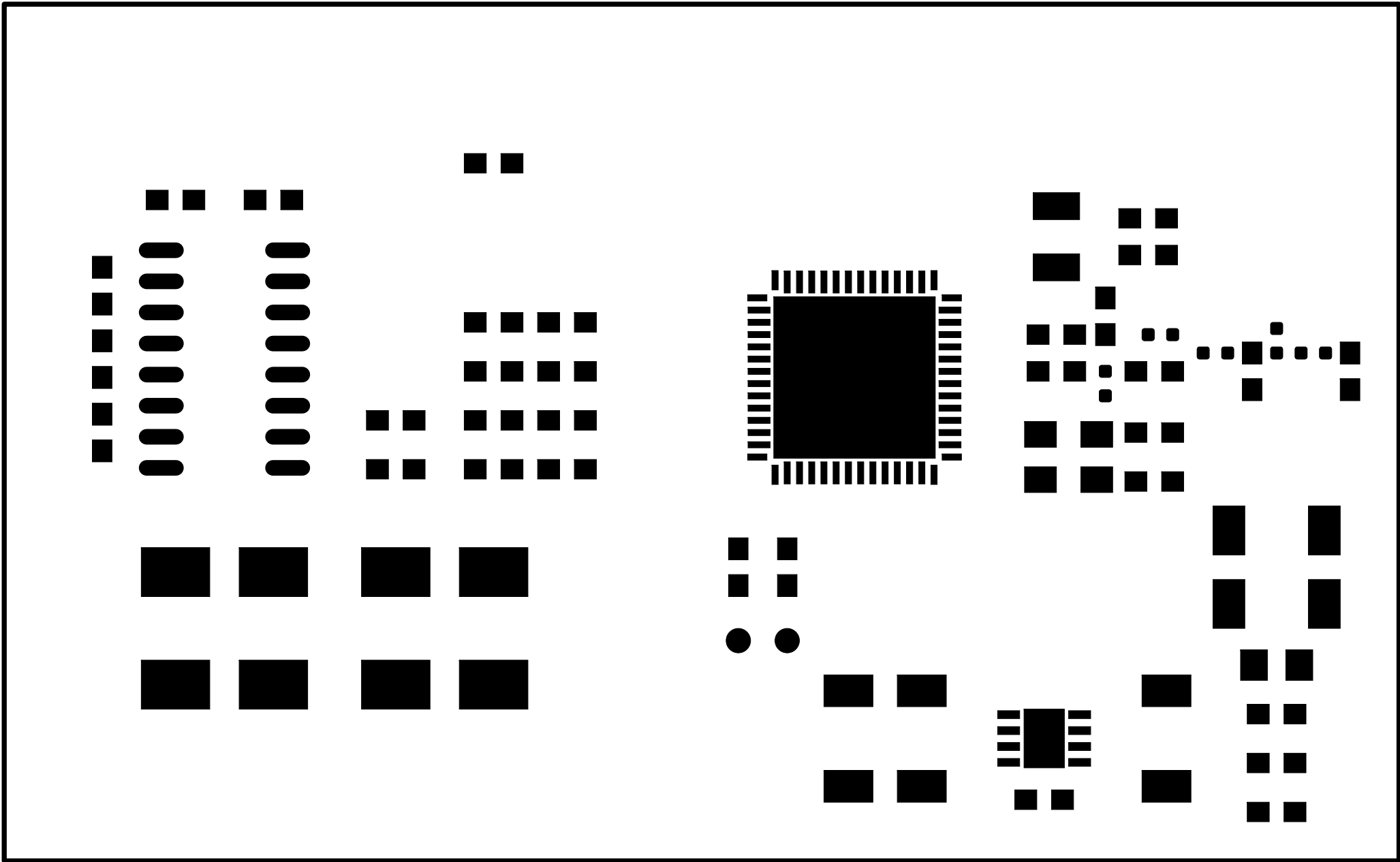
Wireless Board Rev.P0

R10
R9





MODEL NAME	LAYER NAME	DATE
WB	FIX1	2016.10.04





MODEL NAME	LAYER NAME	DATE
WB	FIX2	2016.10.04

